

Arnitel® EL740-08

TPC-ET

Injection Molding, Food Contact Quality

Properties	Typical Data	Unit	Test Method
Rheological properties			
	Value		
Melt volume-flow rate	18	cm ³ /10min	ISO 1133
Temperature	230	°C	ISO 1133
Load	2.16	kg	ISO 1133
Molding shrinkage [parallel]	1.75	%	Sim. to ISO 294-4
Molding shrinkage [normal]	2	%	Sim. to ISO 294-4
Mechanical properties			
	Value		
Shore D Hardness (3s)	70	-	ISO 868
Tensile modulus	800	MPa	ISO 527-1/-2
Yield stress	36	MPa	ISO 527-1/-2
Yield strain	17	%	ISO 527-1/-2
Stress at break	43	MPa	ISO 527-1/-2
Nominal strain at break	360	%	ISO 527-1/-2
Stress at 5% strain	30	MPa	ISO 527-1/-2
Stress at 10% strain	34	MPa	ISO 527-1/-2
Stress at 50% strain	25	MPa	ISO 527-1/-2
Stress at 100% strain	26	MPa	ISO 527-1/-2
Charpy notched impact strength (+23°C)	10	kJ/m ²	ISO 179/1eA
Charpy notched impact strength (-30°C)	6	kJ/m ²	ISO 179/1eA
Izod notched impact strength (+23°C)	9	kJ/m ²	ISO 180/1A
Tear strength	215	kN/m	ISO 34-1; Method B
Compression Set under constant strain at 70 °C	35	%	ISO 815



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Properties	Typical Data	Unit	Test Method
Thermal properties			
Melting temperature (10°C/min)	221	°C	ISO 11357-1/-3
Temp. of deflection under load (0.45 MPa)	120	°C	ISO 75-1/-2
Vicat softening temperature (50°C/h 50N)	160	°C	ISO 306
Coeff. of linear therm. expansion (parallel)	1.65	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	1.65	E-4/°C	ISO 11359-1/-2
Burning Behav. at 1.5 mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.5	mm	IEC 60695-11-10
Electrical properties			
Relative permittivity (100Hz)	3.7	-	IEC 62631-2-1
Relative permittivity (1 MHz)	3.3	-	IEC 62631-2-1
Dissipation factor (1 MHz)	300	E-4	IEC 62631-2-1
Volume resistivity	1E13	Ohm*m	IEC 62631-3-1
Electric strength	23	kV/mm	IEC 60243-1
Comparative tracking index	600	V	IEC 60112
Other properties			
Density	1290	kg/m ³	ISO 1183
Apparent density	830	kg/m ³	ISO 60
Water absorption	0.6	%	Sim. to ISO 62
Humidity absorption	0.15	%	Sim. to ISO 62

